

| | | | | | | | |
|---|-----------------|---|---------|---|----------|-----------------|--|
| LIST OF REFERENCES CITED BY APPLICANT <i>(Use several sheets if necessary)</i> | | | | ATTY. DOCKET NO. | | APPLICATION NO. | |
| | | | | 9818-053-999 | | To be assigned | |
| | | | | APPLICANT | | | |
| | | | | Donald S. Fritz; SEMICONDUCTOR PACKAGE WITH STRESS INHIBITING INTERMEDIATE MOUNTING SUBSTRATE | | | |
| FILING DATE | | | | GROUP 2827 | | To be assigned | |
| Filed Herein | | | | | | | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| EXAMINER INITIAL | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | | |
| | | | | | | | |
| FOREIGN PATENT DOCUMENTS | | | | | | | |
| | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION | |
| | | | | | | YES NO | |
| OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | |
| BV | AA | M.S. Cole, G.B. Martin, P.J. Brofman and L.S. Goldman, "CBGA Fatigue Life Improvement," <i>Proceedings of the Semiconductor Packaging Technologies Symposium</i> , Semicon West '99, Hopewell Jct., New York (1999). | | | | | |
| BV | AB | B.V. Fasano, R. Indyk, D. O'Connor, A.L. Plachy and S.N.S. Reddy, "Glass Ceramic Substrates for Flip Chip Packages," IBM Corporation website, at http://www.chips.ibm.com/products/interconnect/documents/swg/ (Oct. 19, 1999). | | | | | |
| BV | AC | R. Kuracina, "Flip Chip Packaging for the Year 2000," IBM Microelectronics, at http://www.chips.ibm.com/products/interconnect/documents/semi98/ (Oct. 19, 1999). | | | | | |
| BV | AD | "Ceramic Ball Grid Array (CBGA)," IBM Microelectronics, Interconnect Products, at http://www.chips.ibm.com/products/interconnect/documents/sc/cbga.html (Oct. 20, 1999). | | | | | |
| BV | AE | Ceramic Ball Grid Array Product Description, IBM Microelectronics, Interconnect Products at http://www.chips.ibm.com/products/interconnect/documents/sc/cga.html (Jul. 19, 2000). | | | | | |
| BV | AF | "Current Material (Al2O3) Issue," Kyocera Corporation Presentation Materials (1999). | | | | | |
| BV | AG | "Glass Ceramic Chip Carriers: Unleash the Power of Your Silicon With a Proven Technology, Now Available at an Affordable Price," IBM Microelectronics product brochure (1998). | | | | | |
| BV | AH | "Laminate: Plastic Ball Grid Array (PBGA)," IBM Microelectronics, Interconnect Products, at http://www.chips.ibm.com/products/interconnect/documents/sc/pbga.html (Oct. 20, 1999). | | | | | |
| BV | AI | "Ovarmolded FC-BGA Package Cross Section," ASAT Presentation Materials. | | | | | |
| BV | AJ | "SCI: Reliability & Design Guide," NTK Communication Media Components Group, NGK Spark Plug Co., Ltd. Presentation Materials. | | | | | |
| BV | AK | "SolderQuik Column Grid Array (CGA)," Winslow Automation, Inc., at http://www.winslowautomation.com/cga.htm (Sept. 29, 1998). | | | | | |
| EXAMINER | | John B. Vaughan | | DATE CONSIDERED | | April 14, 2003 | |
| *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |

Paper No 2